

1st IEEE International Conference on Industrial Cyber-Physical Systems ICPS2018

Special Session on

“Bringing Cyber-Physical-Systems into industrial practice”

organized by

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Call for Papers

Scope of the Special Session (~200 Words):

Industrial systems are changing rapidly. An increased digitalization of industrial systems is leading to more flexible, more agile and smarter manufacturing. This shift of paradigms affects many different components of a production system. Lower level systems such as field and control devices need to be adapted to be able to comply with these new technologies. The same applies to higher level systems, such as simulation & analytics tools. To bring everything together, integration platforms have to be used. This Special Session is targeted at researchers and industrialists to present and discuss research work related to the integration of new technologies related to the areas of Cyber-Physical Systems, System-of-Systems and Service-Oriented Architecture into new or existing tools or industrial applications.

Topics of interest include, but are not limited to (~100 Words):

- Industry Architectures for Cyber-Physical Systems
- Data Models for Industrie 4.0
- Industrial Middleware

A good quality paper may be considered for publication in IEEE Transactions on Industrial Informatics (TII) - subject to further rounds of review

- CPS-compliant simulation tools
- CPS-compliant analytics tools

Submissions Procedure: All the instructions for paper submission are included in the conference website <http://icps2018.net/>

Deadlines:

Deadline for submission of papers:	22 Dec 2017	15 Feb 2018
Notification of acceptance of papers:	28 Feb 2018	10 Mar 2018
Final manuscripts due:	31 Mar 2018	

International Program Committee (Reviewers) for the Special Session

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